# BES2720IH

Brief Datasheet

## Ultra-low Power Bluetooth Audio Platform


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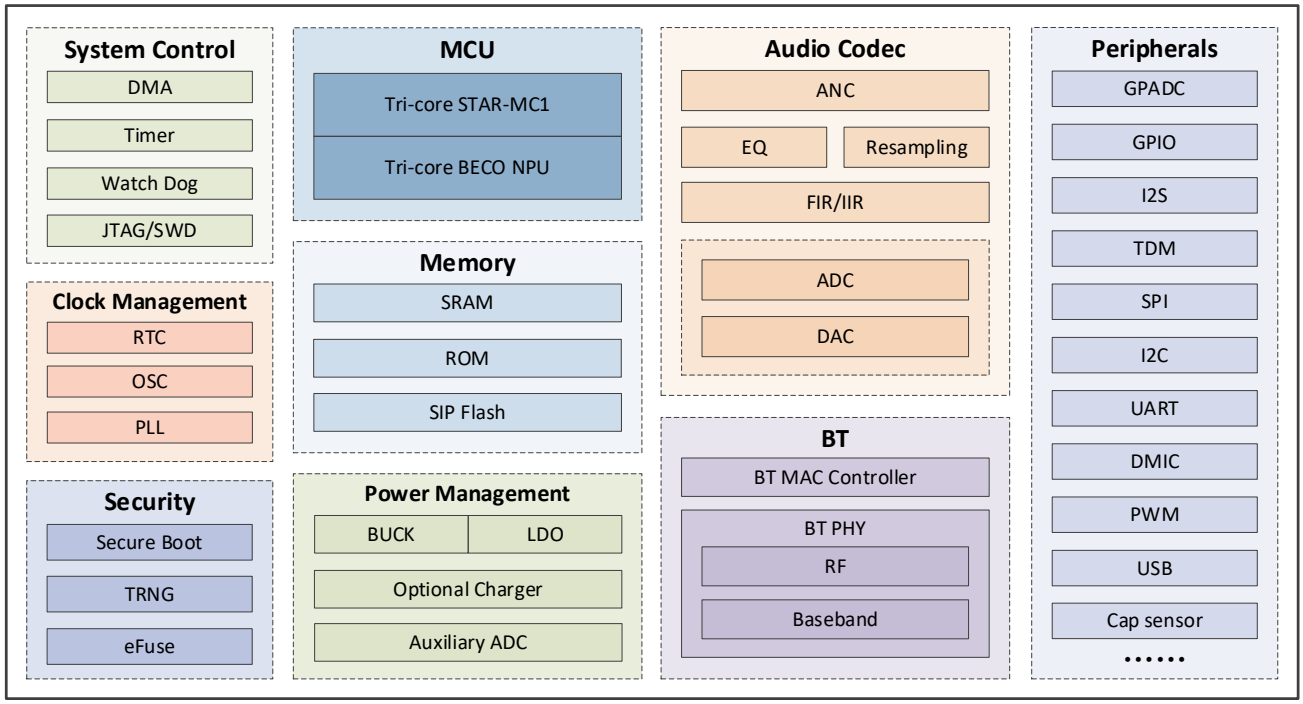
# 1 General Description

The BES2720IH is ultra-low power, high performance Bluetooth audio SoC. The platform incorporates high performance CPU subsystem comprising tri-core STAR-MC1 processor with tri-core BES proprietary coprocessor (BECO) for advanced signal processing and NN workloads, RAM/ROM, flash for software features and product customization, as well as rich interfaces.

The platform incorporates dual-mode Bluetooth 6.1 subsystem supporting BT/BLE/HDT. Furthermore, the platform integrates audio codec subsystem. The design minimizes external components, reduces BOM costs and offers cost-effective Bluetooth audio solution.




System Block Diagram

## 1.1 Applications

- Smart TWS and clip-on earbuds
- Other portable audio devices

## 1.2 Features & Specifications*

| | |
|---|---|
| CPU Subsystem | Tri-core STAR-MC1 |
| Memory and Storage | Shared 1 MB SRAM |
| | Flash in package |
| | boot ROM |
| Bluetooth Subsystem | Dual-mode BT 6.1 with Channel Sounding |
| | HDT support (final spec revision subject to SIG certification) |
| Audio & Voice Features | 2x DACs |
| | 3x ADCs |
| Peripheral Interfaces | GPADC/GPIO/I2S/TDM/SPI/I2C/UART/DMIC/PWM/USB/Cap sensor…… |
| Package | 56-pin QFN |

* The content in the table is subject to change without notice.